

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3856730

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TSUTOMU HIYAMA	04/27/2016
HIROYUKI INOUE	04/27/2016
SHUNSUKE KIMOTO	04/27/2016
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23, SENJU-HASHIDO-CHO, ADACHI-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1208555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14906660
CORRESPONDENCE DATA	
Fax Number:	(412)471-4094
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	412-471-8815
Email:	assignments@webblaw.com
Correspondent Name:	THE WEBB LAW FIRM, P.C.
Address Line 1:	ONE GATEWAY CENTER
Address Line 2:	420 FT. DUQUESNE BLVD, SUITE 1200
Address Line 4:	PITTSBURGH, PENNSYLVANIA 15222
ATTORNEY DOCKET NUMBER:	7466-1511375
NAME OF SUBMITTER:	BRYAN P. CLARK
SIGNATURE:	/Bryan P. Clark/
DATE SIGNED:	05/03/2016
Total Attachments: 4	
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RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Tsutomu HIYAMA
Hiroyuki INOUE
Shunsuke KIMOTO

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) April 27, 2016

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)

Name: Senju Metal Industry Co., Ltd.

Internal Address: _____

Street Address: 23, Senju-Hashido-cho, Adachi-ku

City: Tokyo

State: _____

Country: JAPAN

Zip: 1208555

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☐ This document serves as an Oath/Declaration (37 CFR 1.63).

A. Patent Application No.(s)

14/906,660

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Russell D. Orkin

Internal Address: The Webb Law Firm

Street Address: One Gateway Center

420 Ft. Duquesne Blvd., Ste 1200

City: Pittsburgh

State: PA Zip: 15222

Phone Number: 412-471-8815

Docket Number: 7466 - 1511375

Email Address: assignments@webblaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 0

- ☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

Deposit Account Number _____

Authorized User Name _____

9. Signature:



Signature

May 3, 2016

Date

Bryan P. Clark

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

INTERNATIONAL
Application No. 14/906,660
Attorney Docket No. 7466-1511375

ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

SOLDERING APPARATUS AND VACUUM-SOLDERING METHOD

(Invention Title)

☐ for which I have this day executed an application for a United States Patent (hereinafter "said application").

AND/OR

☒ for which an application for a United States Patent was filed on 07/23/2013 (mm/dd/yyyy) and bears Application Number 14/906,660 (hereinafter "said application").

AND/OR

☒ for which an international patent application was filed under the Patent Cooperation Treaty on 07/23/2013 (mm/dd/yyyy), bearing Application No. PCT/JP2013/069933 (hereinafter "said application").

AND, WHEREAS, **Senju Metal Industry Co., Ltd.**, a corporation of **Japan**, having a place of business at **23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan**, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

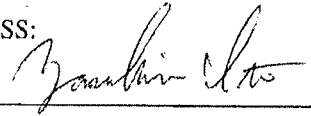
1. FULL NAME OF ASSIGNOR:
Tsutomu HIYAMA

RESIDENCE:
Tokyo, Japan

EXECUTED this 27th day of April, 2016


SIGNATURE

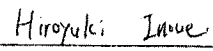
WITNESS:



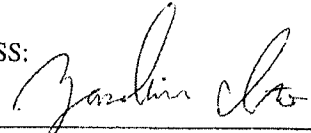
2. FULL NAME OF ASSIGNOR:
HiroYuki INOUE

RESIDENCE:
Tokyo, Japan

EXECUTED this 27th day of April, 2016


SIGNATURE

WITNESS:



☒ Checked Box indicates 1 additional page(s) for inventor signatures.

INTERNATIONAL
Application No. 14/906,660
Attorney Docket No. 7466-1511375

3. FULL NAME OF ASSIGNOR:
Shunsuke KIMOTO

RESIDENCE:
Tokyo, Japan

EXECUTED this 27th day of April, 2016

Shunsuke KIMOTO
SIGNATURE

WITNESS:

